

Structural Bonding

STRUCTURAL	STRUCTURAL BONDING	LOCTITE ECCOBOND EO1016	LOCTITE ECCOBOND EO1072	LOCTITE SI 5084
BONDING	EMI SHIELDING	LOCTITE SI 5421	LOCTITE ABLESTIK 59C	
LENS BONDING & SEALING	OPTICAL LENS BONDING	LOCTITE ECCOBOND LUX 3042M	LOCTITE HHD 4042	
	LENS SEALING	LOCTITE 3119		

Structural Bonding

PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	VISCOSITY (cP)	GLASS TRANSITION TEMPERATURE, T _g (°C)	CURE TYPE	CURE SCHEDULE	
STRUCTURAL BONDING								
LOCTITE ECCOBOND E01016	Ероху	Encapsulant	Good adhesion to metal and plastics, especially nickel and FR4 Fast curing Excellent shelf stability	62,000	126	Heat	20 min. at 150°C	
LOCTITE ECCOBOND E01072	Ероху	Encapsulant	High Tg Low extractable ionics High performance Good shelf life Fast curing	100,000	135	Heat	5 min. at 140 - 150°C	
LOCTITE SI 5084	Silicone	Gasketing	Highly flexible Non-corrosive Enhances load bearing and shock absorbing characteristics of the bond area	Paste	N/A	UV & RT	UV + Moisture	
EMI SHIELDING								
LOCTITE SI 5421	Silicone	Bonding/Gasketing	Electrically conductive RTV silicone Bonding and gasketing of EMI/RFI shielded enclosures	Paste	N/A	RTV	Tack free in 60 min. at 23 ±2°C / 50 ±5% RH	
LOCTITE ABLESTIK 59C	Silicone	Assembly	Electrically conductive silicone EMI / RFI shielding Thermally conductive High flexibility High tack Can be used with a variety of catalysts	N/A	N/A	Heat	6 hr. at 150°C	

Lens Bonding & Sealing

PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	VISCOSITY (cP)	GLASS TRANSITION TEMPERATURE, T _g (°C)	CURE TYPE	CURE SCHEDULE	
OPTICAL LENS BONDING	OPTICAL LENS BONDING							
LOCTITE ECCOBOND LUX 3042M	Acrylate	Assembly	One component Dual cure system Good adhesion on PEI plastics, FR4 and various other substrates	85,000	114	UV & Heat	UV + 30 min. at 120°C	
LOCTITE HHD 4042	Epoxy/Acrylate	Assembly	One component Dual cure system Good adhesion on PEI plastics, FR4 and various other substrates	125,000	145	UV & Heat	UV + 60 min. at 120°C	
LENS SEALING								
LOCTITE ABLESTIK 3119	Ероху	Bonding	Low temp cure Excellent adhesion on wide range of substrates Very low shrinkage	7,000 - 23,000	110	Heat	60 min. at 100°C or 20 min. at 75°C	

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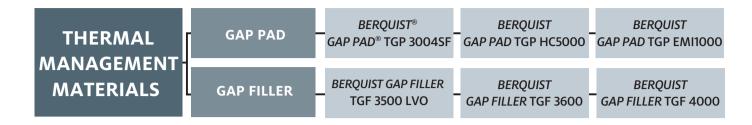


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Thermal Management Materials



PRODUCT	TECHNOLOGY	APPLICATION	KEY ATTRIBUTES	THICKNESS (in/mm)	SHORE HARDNESS (SHORE 00)	THERMAL CONDUCTIVITY (W/m-K)	
THERMAL PAD							
BERQUIST GAP PAD TGP 3004SF	Silicone Free	Thermal Pad	Silicone-Free formulation O.25 mil PET provides easy disassembly, leaving no residue Tacky side allows for ease of handling and placement	0.254 ~ 3.175	70	3.0	
BERQUIST GAP PAD TGP HC5000	Silicone	Thermal Pad	High-compliance Low compression stress Fiberglass reinforced for shear and tear resistance	0.508 ~ 3.175	35	5.0	
EMI ABSORPTION							
BERQUIST GAP PAD TGP EMI1000	Silicone	EMI Absorbing	EMI absorbing Highly conformable Low hardness Fiberglass reinforced for puncture, tear and shear resistance Electrically isolating	0.508 - 3.175	5	1.0	
GAP FILLER							
BERQUIST GAP FILLER TGF 3500LVO (TWO PARTS)	Silicone	Gap Filler	Low volatility for outgassing sensitive applications Ultra-conforming with excellent wet-out for low stress interface on applications 100% solids - no cure by-products	N/A	40	3.5	
BERQUIST GAP FILLER TGF 3600	Silicone	Gap Filler	Thixotropic nature makes it easy to dispense Two-part formulation for easy storage Ultra-conforming - designed for fragile and low stress applications Ambient or accelerated cure schedules	N/A	35	3.6	
BERQUIST GAP FILLER TGF 4000	Silicone	Gap Filler	Thickness variations Little to no stress 100% Solids – No cure by-products Excellent low and high temperature chemical and mechanical stability	N/A	75	4.0	

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